

ABSTRACT

The present invention relates to a first protective film-forming sheet formed by stacking a first pressure-sensitive adhesive layer on a first base material and stacking a
5 curable resin layer on the first pressure-sensitive adhesive layer, in which the curable resin layer is a layer to form a first protective film on a bump-provided surface of a semiconductor wafer by being attached to the surface and cured, a sum of a thickness of the curable resin layer and a thickness of a first pressure-sensitive adhesive layer is 110 μm or more, and the thickness of the curable resin layer is 20 μm to 100 μm .